Notice of Allowability	Application No.	Applicant(s)	
	10/702,561	SHIZUNO, YOSHINORI	
	Examiner	Art Unit	
	Jasmine J Clark	2815	
The MAILING DATE of this communication apperature All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIOF the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this app or other appropriate communication GHTS. This application is subject to	olication. If not include will be mailed in due	ed course. <b>THIS</b>
1. This communication is responsive to			
2. 🔀 The allowed claim(s) is/are <u>1-14</u> .			
3. 🔀 The drawings filed on <u>07 November 2003</u> are accepted by the Examiner.			
4.			
Attachment(s)  1. ☑ Notice of References Cited (PTO-892)  2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948)  3. ☑ Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date 11/07/03  4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material	5. ☐ Notice of Informal P 6. ☐ Interview Summary Paper No./Mail Dat 8), 7. ☐ Examiner's Amendr 8. ☑ Examiner's Stateme 9. ☐ Other	(PTO-413), e nent/Comment	·
	P	JASMINE CLARK RIMARY EXAMINE	:R

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#### **DETAILED ACTION**

#### Information Disclosure Statement

1. The Information Disclosure Statement filed 11/07/2003 has been fully considered and made of record.

### References Cited

2. Saeki (US 6,717,252 B2) shows a structure of a semiconductor device comprising a substrate (region 30A having a first surface and a second surface opposed to the first surface; a semiconductor chip 11 (see Fig. 2) having a third surface and a fourth surface opposed to the third surface, and mounted on the first surface; wherein the semiconductor chip 11 includes: a plurality of electrode pads 12 formed on the third surface, an insulating layer 16 which is formed on the third surface, a plurality of bump electrodes 15 disposed over the insulating layer, wiring 14 formed in the insulating layer to electrically connect the bump electrode to the pads, external terminals 17 disposed on the first surface of the substrate; and a sealing resin 44 for sealing the first surface and the semiconductor chip. However, Saeki fails to teach that the insulating layer which is formed on the third surface and which includes an opening for exposing a part of the surface of each electrode pad having the conductive trace formed on the insulating, and the wiring formed on the insulating layer as the claimed invention.

The references of interest are cited: Please also see Hayashida et al. (US 6,060,768), Schueller (US 5,866,949), Frye et al. (US 5,898,223), Ohsawa et al. (US 6,054,773), Chen et al. (US 6,765,277 B2), Shim et al. (US 6,414,396 B1),

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Akram et al. (US 6,407,451 B2), Kim (US 6,380,629 B1), Palagonia (US 5,874,782), Fischer et al. (US 5,701,032)Miura et al. (US 5,565,706), Hashimoto (US 6,414,382 B1), Kwon et al. (US 6,407,459 B2), and Kameyama et al. (US 6,281,570 B1).

## Allowable Subject Matter

3. Claims 1-14 are allowed.

The following is an examiner's statement of reasons for allowance: please see the above discussion.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

# Telephone Inquiry Contacts

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jasmine J Clark whose telephone number is (571) 272-1726. The examiner can normally be reached on Flex.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on (571) 272-1664. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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